



US00D920937S

(12) **United States Design Patent**  
**Umeda et al.**

(10) **Patent No.:** **US D920,937 S**  
(45) **Date of Patent:** **\*\* Jun. 1, 2021**

(54) **POWER MODULE DEVICE CONTAINING SEMICONDUCTOR ELEMENTS**

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(\*\*) Term: **15 Years**

(21) Appl. No.: **35/508,564**

(22) Filed: **Mar. 29, 2019**

(80) **Hague Agreement Data**

Int. Filing Date: **Mar. 29, 2019**

Int. Reg. No.: **DM/205733**

Int. Reg. Date: **Mar. 29, 2019**

Int. Reg. Pub. Date: **Feb. 14, 2020**

(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/182  
CPC ... H01L 23/29; H01L 21/221; H01L 23/3735;  
H01L 25/18; H01L 23/4006; H01L  
23/49541; H05K 1/115

See application file for complete search history.

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(Continued)

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(57) **CLAIM**

The ornamental design for a power module device containing semiconductor elements, as shown and described.

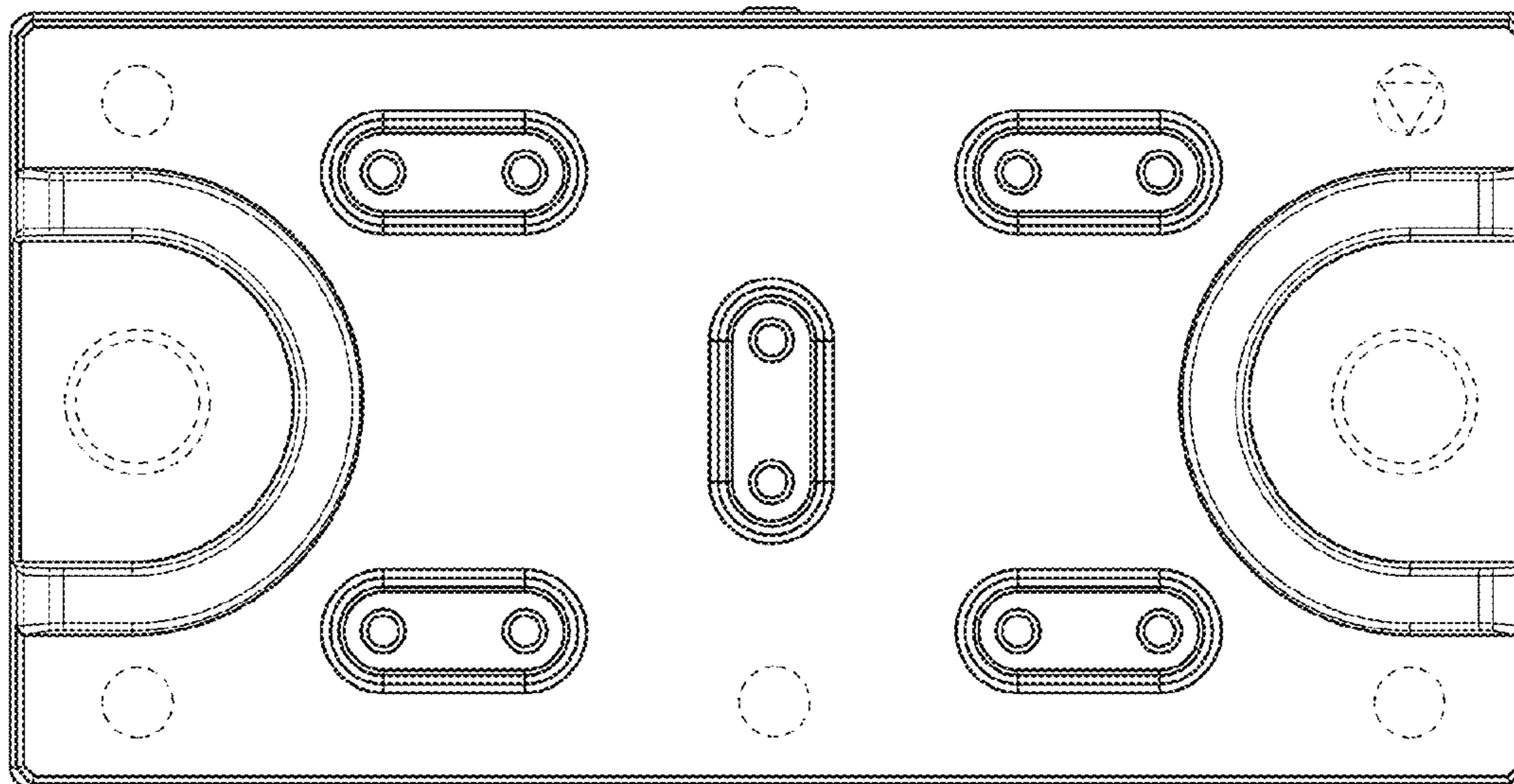
**DESCRIPTION**

- 1. Power module device containing semiconductor elements
- 1.1 : Front
- 1.2 : Back
- 1.3 : Top
- 1.4 : Bottom
- 1.5 : Right
- 1.6 : Left
- 1.7 : Perspective

The broken lines showing portions of the power module device containing semiconductor elements form no part of the claim.

This article is a power module device containing semiconductor elements; this product is used to control and/or supply electric power.

**1 Claim, 7 Drawing Sheets**



(56)

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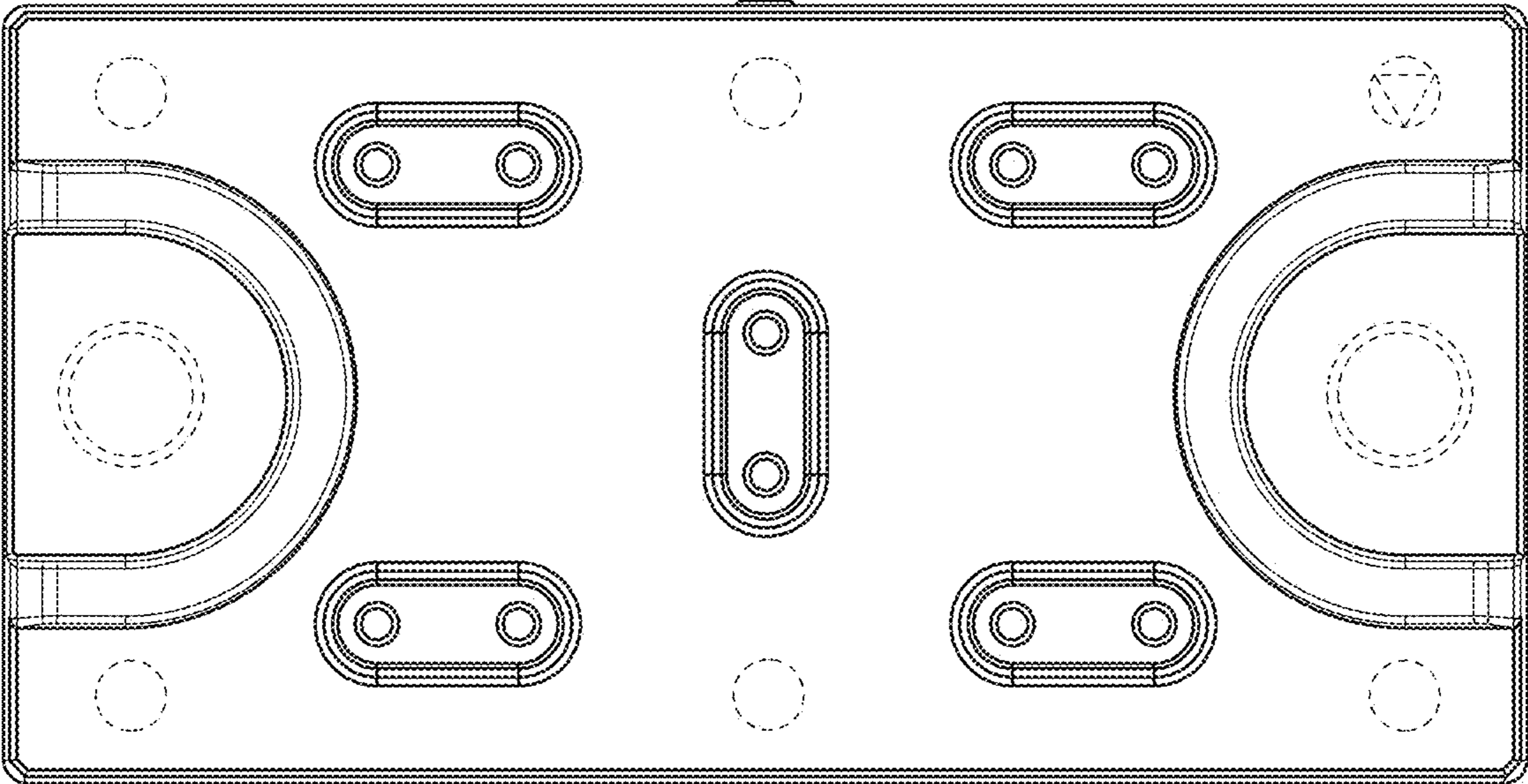


FIG. 1.1

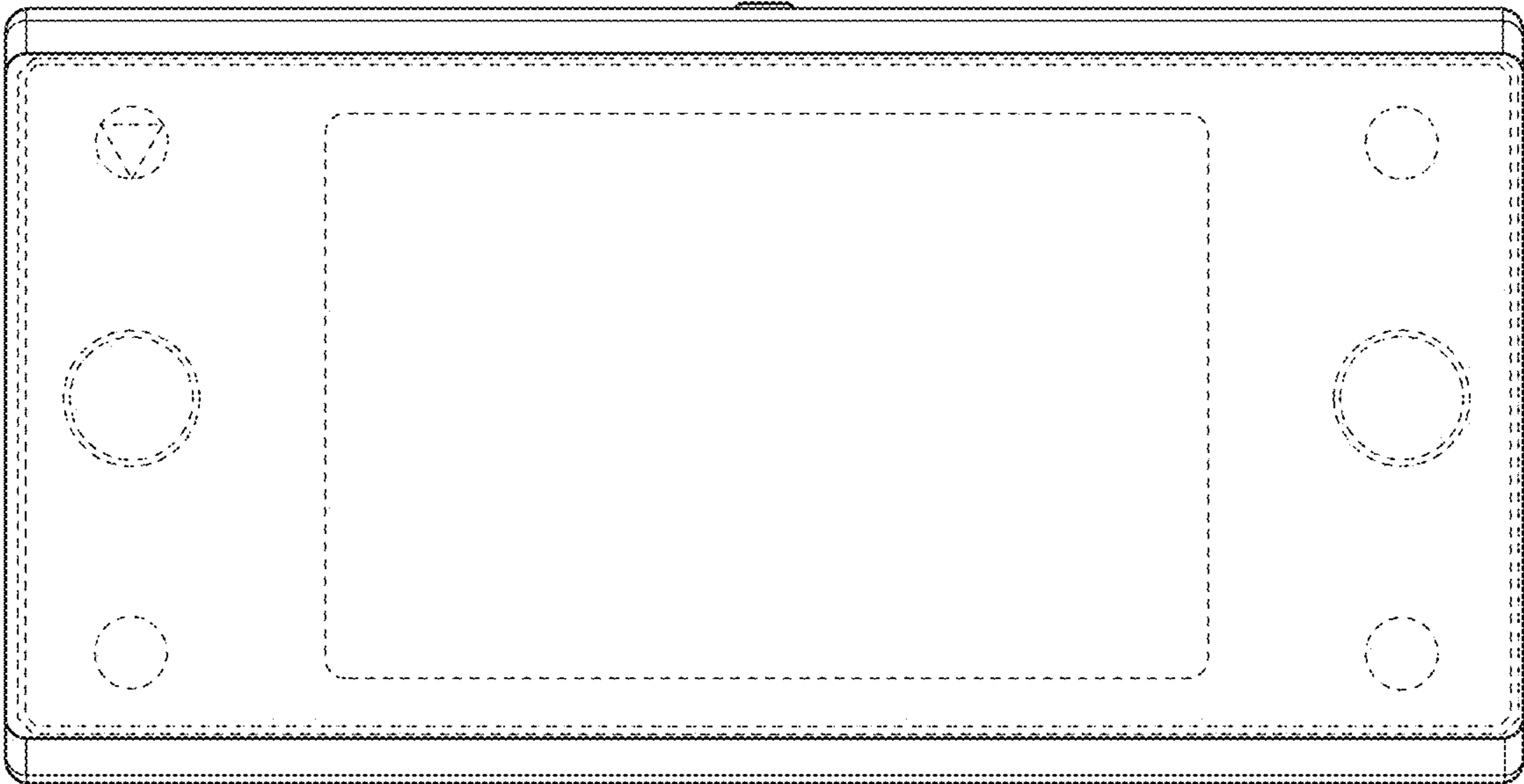
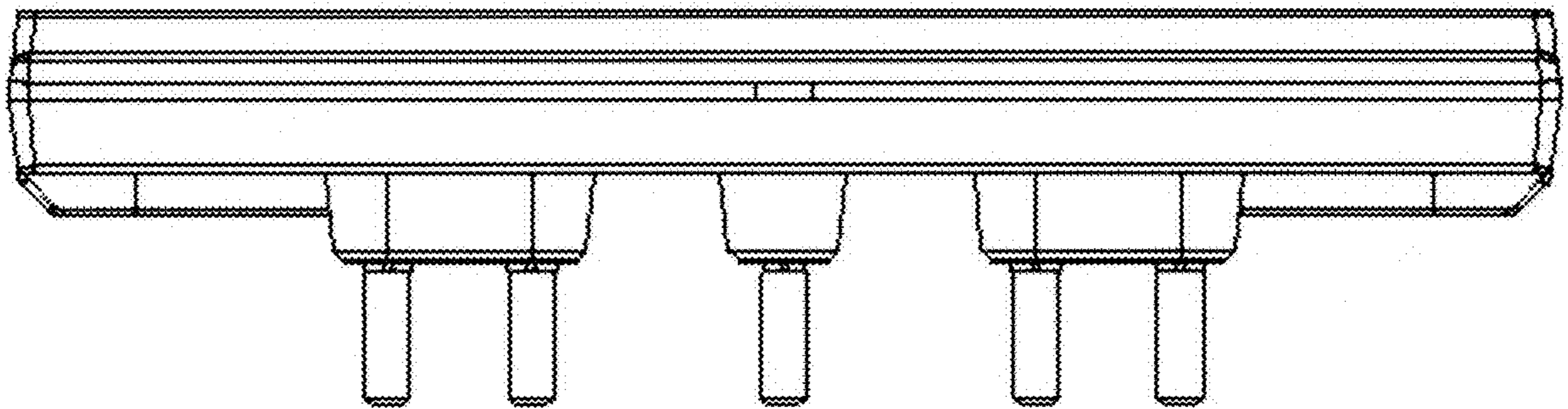
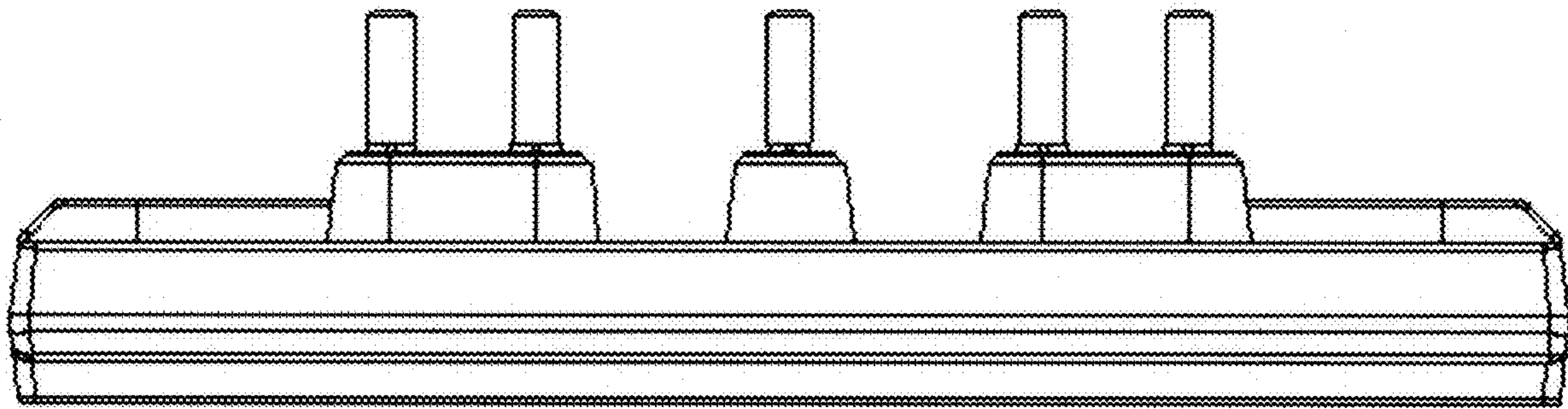


FIG. 1.2

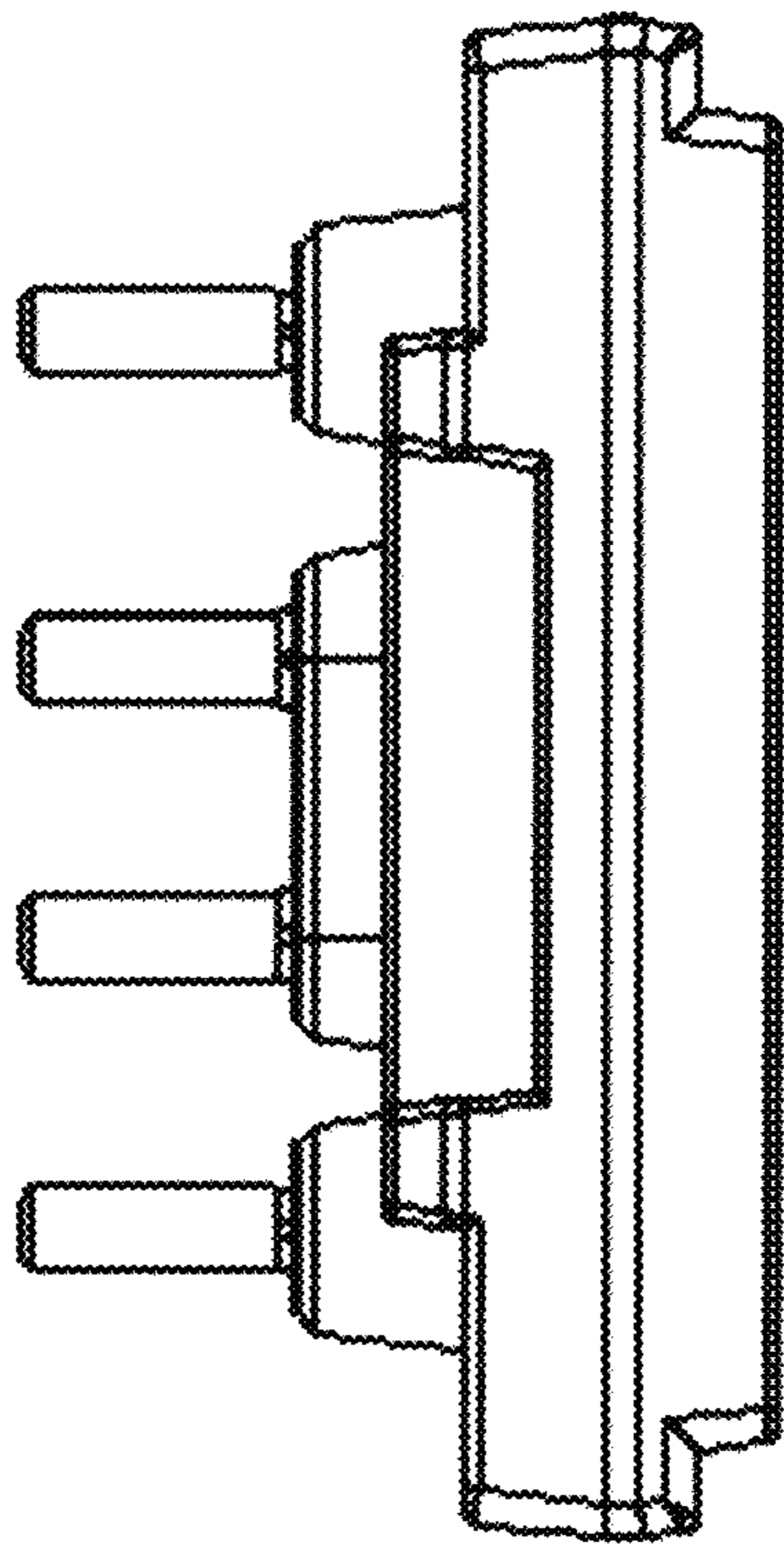
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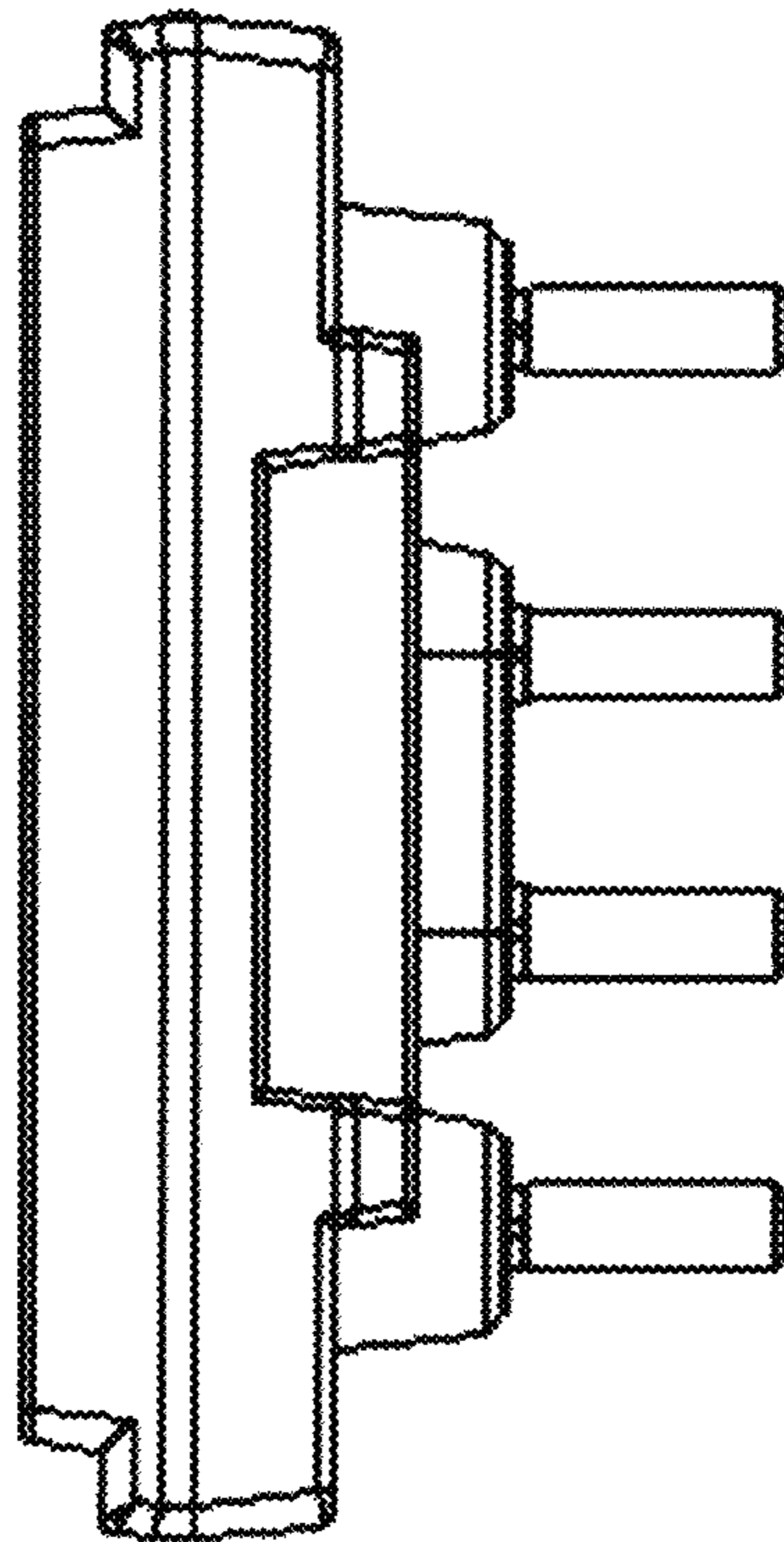
1.4



1.5



1.6





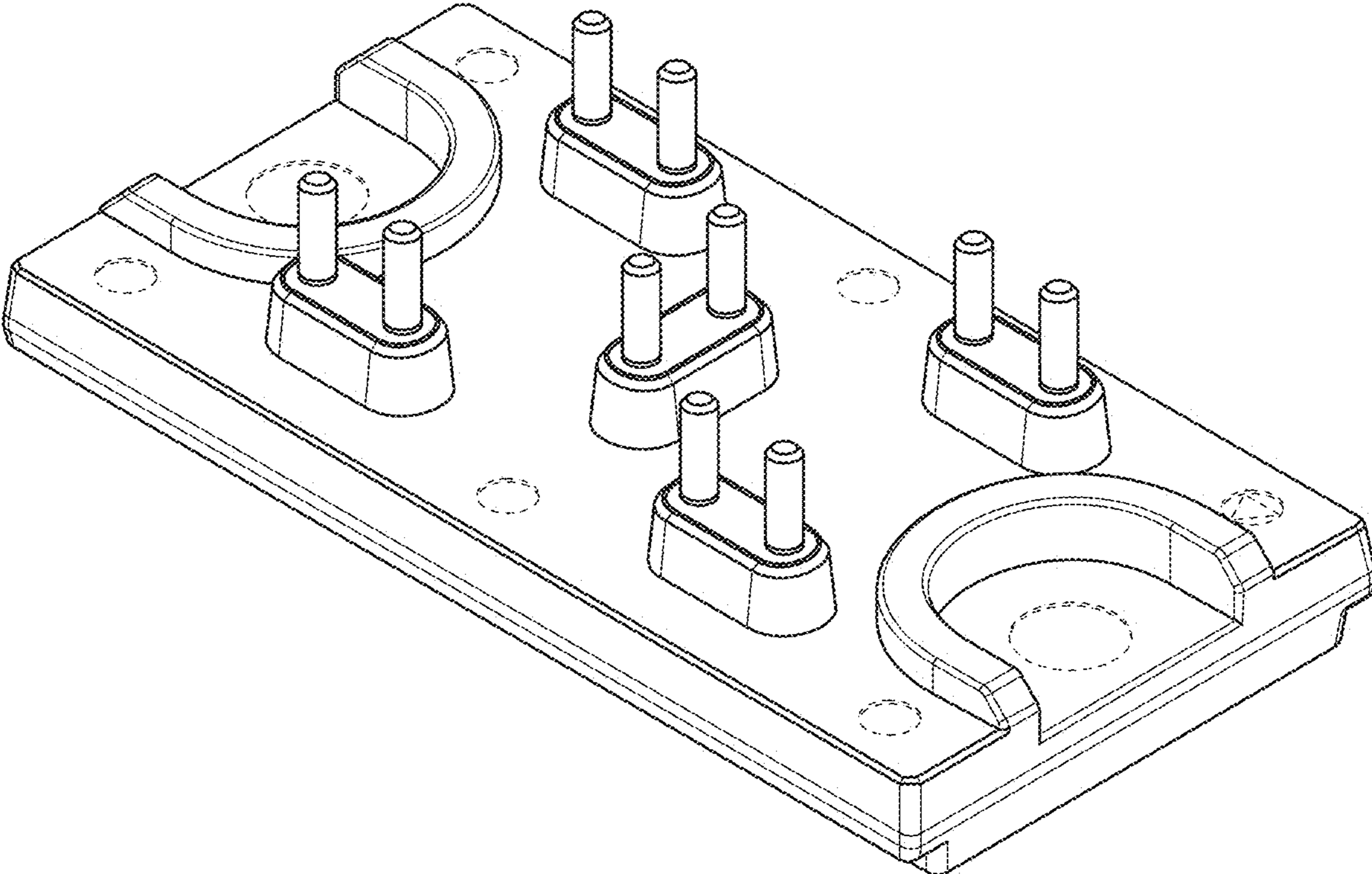


FIG. 1.7